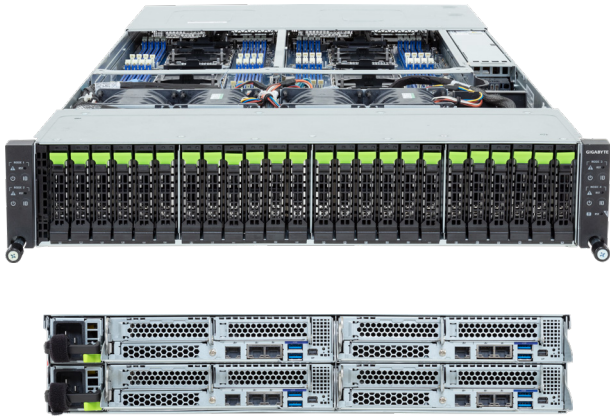


H274-S60-AAW1

High Density Server - 2U 4-Node DP 24-Bay NVMe/SATA



Key Features

- 2U 4-node rear access server system
- Dual Intel® Xeon® 6 Processors, LGA 4710
- 8-Channel DDR5 RDIMM / MCR DIMM, 16 x DIMMs per node
- Dual ROM Architecture
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 24 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swappable bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 8 x LP PCIe Gen5 x16 slots
- 4 x OCP 3.0 Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Application

High-Performance Computing Server, High Converged Server

Specification

Dimensions	2U 4-Node - Rear access (W438 x H87.5 x D877 mm)	Internal I/O	Per node: 1 x TPM header, 1 x PRoT connector, 1 x VROC connector
Motherboard	MS64-HD0	Backplane Board	Speed & bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700E-Series Processors - Intel® Xeon® 6700P-Series Processors - Intel® Xeon® 6500P-Series Processors Dual processors per node, TDP up to 225W	Security Modules	1 x TPM header with SPI interface per node - Optional TPM2.0 kit: CTM012 1 x PRoT module connector (M.2 M-key) per node - Optional PRoT module (AST1060 solution): CSC1200
Sock	2 x LGA 4710 per node (Socket E2)	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Chipset	System on Chip	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	Total 64 x DIMM slots (16 x DIMM slots per node) 8-Channel DDR5 RDIMM / MCR DIMM RDIMM: Up to 6400 MT/s; MCR DIMM: Up to 8000 MT/s *MCR DIMMs are only supported with Intel Xeon 6 Processors with P-cores.	System Fans	4 x 80x80x80mm (16,500rpm)
LAN	8 x 1Gb/s LAN ports (4 x Intel® I350-AM2) - Support NCSI function 4 x 10/100/1000 Mbps Management LAN	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter Management chip on CMC board: Integrated in ASPEED® AST2620	Packaging Content	1 x H274-S60-AAW1 8 x CPU heatsinks 16 x Carriers 1 x 3-Section Rail kit
Storage	Total 24 x 2.5" Gen5 NVMe/SATA/SAS-4* hot-swappable bays *SAS card is required to support SAS drives.	Part Numbers	Barebone package: 6NH274S60DR000AAW1* - 3-Section Rail kit: 25HB2-A66125-K0R - CPU heatsink: 25ST1-253108-C1R/25ST1-253109-C1R - Power supply: 25EP0-23000V-LOS - C19 power cord 125V/15A (US): 25CP3-018000-Q0R (optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R (optional) - M.2 riser card - CMTP160: 9CMTP160NR-00 (optional)
RAID	Require RAID add-in cards		
Expansion Slots	8 x LP PCIe Gen5 x16 slots 4 x OCP 3.0 Gen5 x16 slots (supports NCSI function) Optional 4 x M.2 slots (CMTP160): M-key, PCIe Gen4 x4, supports 2260/2280/22110 cards		
Rear I/O	Per node: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN		



Learn more about GIGABYTE server at <https://www.gigabyte.com/Enterprise>

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